



Features

- Average Forward Current: $I_{F(AV)}=2A$
- Polarity: Color band denotes cathode



SMA
(DO-214AC)

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
US2A-US2M	SMA (DO-214AC)	US2x	2000

x: From A-M



Maxmim Ratings (Ta=25 unless otherwise noted)

Item	Symbol	Unit	Test Conditions	US2							
				A	B	D	E	G	J	K	M
Repetitive Peak Reverse Voltage	V _{RRM}	V		50	100	200	300	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V		35	70	140	210	280	420	560	700
Average Forward Current	I _{F(AV)}	A	60Hz Half-sine wave, Resistance load, FIG.1	2.0							
Surge(Non-repetitive)Forward Current	I _{FSM}	A	60Hz Half-sine wave, 1 cycle, Ta=25℃	60							
Junction Temperature	T _J	℃		-55~+125			-55~+150				
Storage Temperature	T _{STG}	℃		-55 ~ +150							

Electrcal Charcteristics (Ta=25 unless otherwise specified)

Item	Symbol	Unit	Test Condition		US2						
					A	B	D	E	G	J	K
Peak Forward Voltage	V _F	V	I _F =2.0A		1.0			1.3		1.85	
Maximum reverse recovery time	T _{rr}	ns	I _F =0.5A, I _R =1.0A, I _{rr} =0.25A		50					75	
Peak Reverse Current	I _{RRM1}	mA	V _{RM} =V _{RRM}	T _a =25℃	0.05						
	T _a =100℃			0.15							
Thermal Resistance(Typical)	R _{θJ-A}	℃/ W	Between junction and ambient		65						
	R _{θJ-L}		Between junction and terminal		20						

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas



Typical Characteristics

FIG.1-TYPICAL FORWARD CHARACTERISTICS

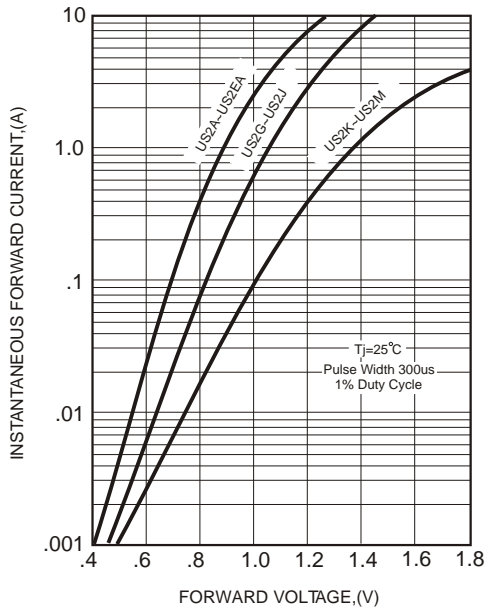
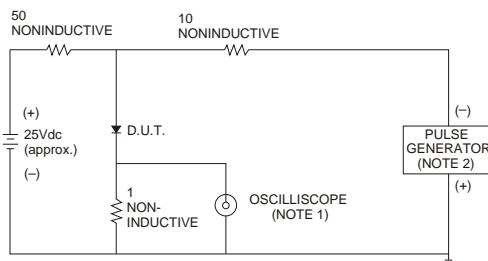


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

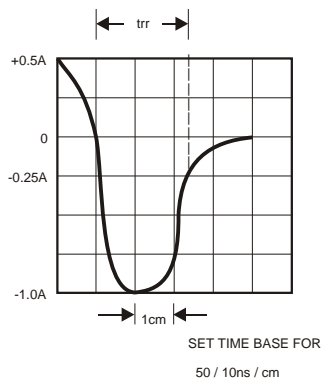


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

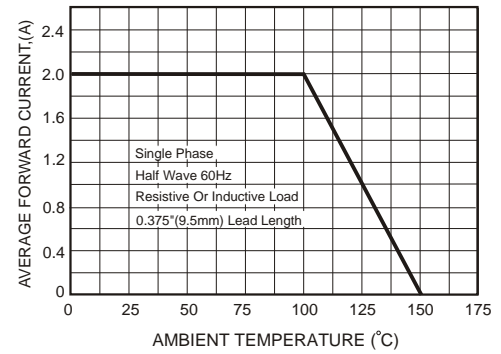


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

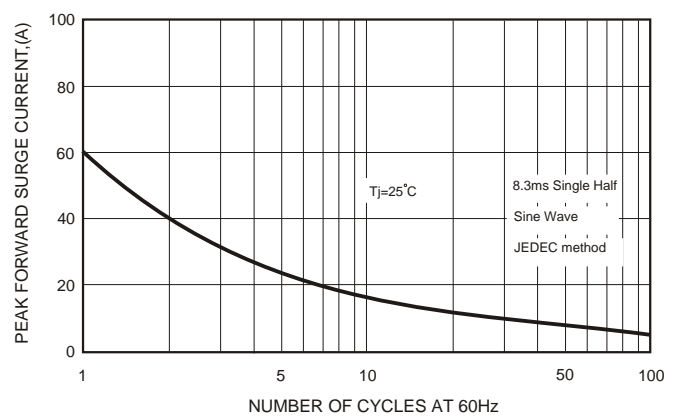
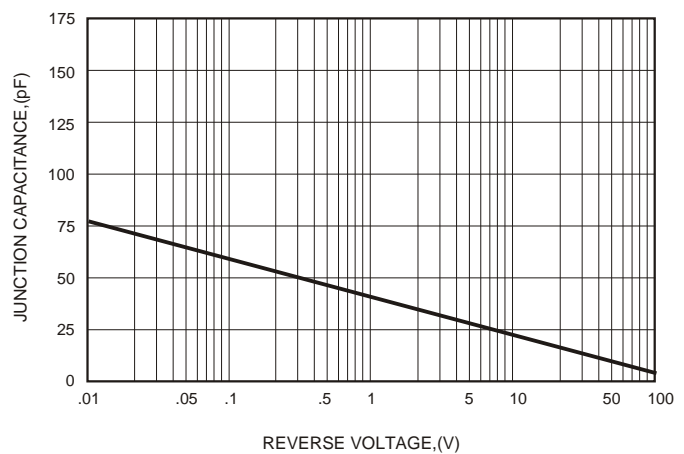
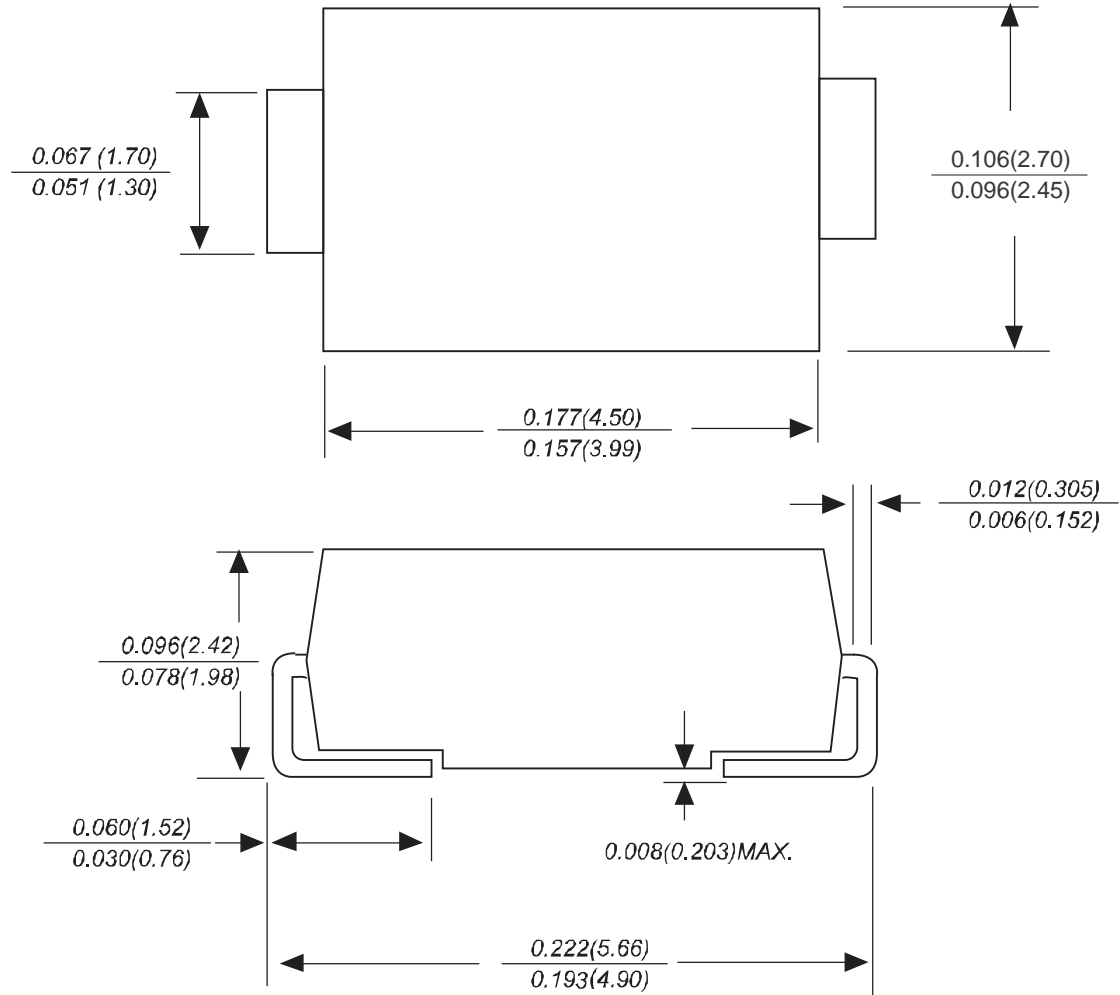


FIG.5-TYPICAL JUNCTION CAPACITANCE





Package Outline Dimensions
SMA(DO-214AC)



Dimensions in inches and (millimeters)



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